

#### **Features**

Solid-state silicon-avalanche technology

Low operating and clamping voltage

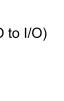
Up to four I/O Lines of Protection

Ultra low capacitance: 0.3pF typical(I/O to I/O)

Low Leakage

Low operating voltage:5V

Flow-Through design



## **Applications**

Digital Visual Interface(DVI)

**MDDI Ports** 

DisplayPort TM Interface

**PCI Express** 

High Definition Multi-Media Interface(HDMI)

eSATA Interfaces

#### **Mechanical Characteristics**

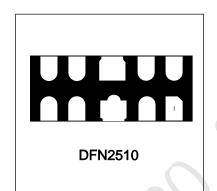
DFN2510 package (2.5×1.0×0.50mm)

Molding compound flammability rating: UL

94V-0

Marking: Marking Code
Packaging: Tape and Reel

**RoHS Compliant** 



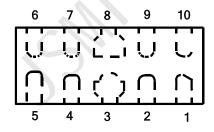
## IEC COMPATIBILITY (EN61000-4)

IEC 61000-4-2 (ESD) ±18kV (air), ±12kV (contact)

IEC 61000-4-4 (EFT) 40A (5/50ns)

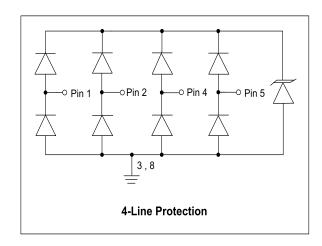
IEC 61000-4-5 (Lightning) 5A (8/20µs)

## **Schematic & PIN Configuration**



Pin	Identificaion	
1,2,4,5	Input Lines	
6,7,9,10	Output Lines (No Internal Connection)	
3,8	Ground	

## **Circuit Diagram**





# **Absolute Maximum Rating**

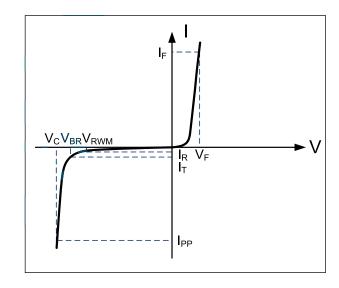
Rating	Symbol	Value	Units	
Peak Pulse Power ( t <sub>p</sub> =8/20μs )	P <sub>PP</sub>	100	Watts	
Peak Pulse Current ( t <sub>p</sub> =8/20µs )	Ірр	5	А	
ESD per IEC 61000-4-2(Air) ESD per IEC 61000-4-2(contact)	V <sub>ESD</sub>	+/-18 +/-12	kV	
Operating Temperature	TJ	-55 to + 125	°C	
Storage Temperature	Тѕтс	-55 to +150	°C	

# **Electrical Characteristics**

Parameter	Symbol	Conditions	Minimum	Typical	Maximum	Units
Reverse Stand-Off Voltage	V <sub>RWM</sub>	Any I/O pin to ground			5.0	٧
Reverse Breakdown Voltage	V <sub>BR</sub>	I <sub>t</sub> = 1mA Any I/O pin to ground	6.0			V
Reverse Leakage Current	I <sub>R</sub>	V <sub>RWM</sub> = 5V, T=25°C Any I/O pin to ground			1	μA
Clamping Voltage	Vc	I <sub>pp</sub> =1A, t <sub>p</sub> =8/20μs Any I/O pin to ground			9	V
Clamping Voltage	Vc	I <sub>pp</sub> =5A, t <sub>p</sub> =8/20μs Any I/O pin to ground			15	٧
	Cj	V <sub>R</sub> = 0V, f = 1MHz I/O pin to GND			0.8	pF
Junction Capacitance		V <sub>R</sub> = 0V, f = 1MHz Between I/O pins		0.3	0.4	pF

# **Electrical Parameters (T=25°C)**

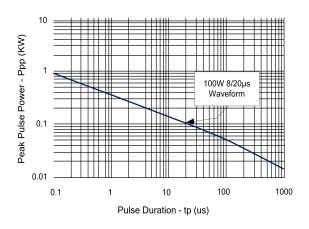
Symbol	Parameter	
<b>I</b> PP	Reverse Peak Pulse Current	
Vc	Clamping Voltage @ IPP	
VRWM	Working Peak Reverse Voltage	
<b>I</b> R	Reverse Leakage Current @ VRWM	
V <sub>BR</sub>	Breakdown Voltage @ I⊤	
lτ	I <sub>τ</sub> Test Current	
<b>I</b> F	Forward Current	
VF	Forward Voltage @ I <sub>F</sub>	



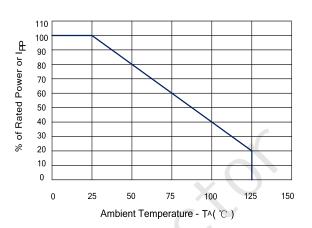


## **Typical Characteristics**

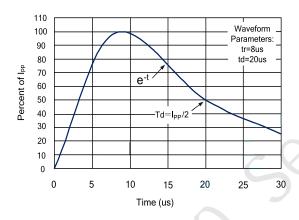
Non-Repetitive Peak Pulse Power vs. Pulse Time



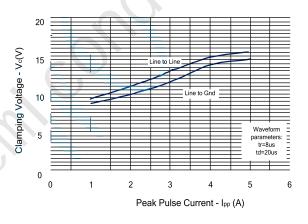
Power Derating curve



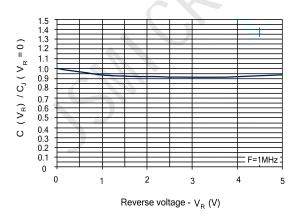
Pulse Waveform



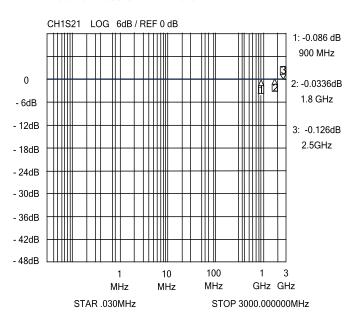
Clamping Voltage vs.Peak Pulse Current



Normalized Capacitance vs. Reverse Voltage



Insertion Loss S21 - I/O to GND





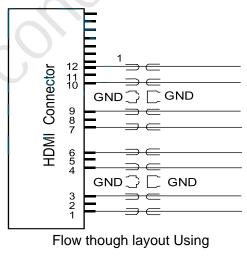
#### **Application Information**

#### Design Recommendations for HDMI protection

Adding external ESD protection to HDMI ports can be challenging. First, ESD protection devices have an inherent junction capacitance. Furthermore, adding even a small amount of capacitance will cause the impedance of the differential pair to drop. Second, large packages and land pattern requirements cause discontinuities that adversely affect signal integrity. The RCLAMP0524P and RCLAMP0522P are specifically designed for protection of high-speed interfaces such as HDMI. They present <0.4pF capacitance between the pairs while being rated to handle ±8kV ESD contact discharges (±15kV air discharge) as outlined in IEC 61000-4-2. Each device is in a leadless SLP package that is less than 1.1mm wide. They are designed such that the traces flow straight through the device. The narrow package and flow-through design reduces discontinuities and minimizes impact on signal integrity. This becomes even more critical as signal speeds increase.

#### **Pin Configuration**

Figure 1 is an example of how to route the high speed differential traces through the RCLAMP0524P. The solid line represents the PCB trace. The PCB traces are used to connect the pin pairs for each line (pin 1 to pin 10, pin 2 to pin 9, pin 4 to pin 7, pin 5 to pin 6). For example, line 1 enters at pin 1 and exits at Pin 10 and the PCB trace connects pin 1 and 10 together. This is true for lines connected at pins 2, 4, and 5 also. Ground is connected at pins 3 and 8. One large ground pad should be used in lieu of two separate pads. The same layout rules apply for the RCLAMP0522P.



RCLAMP0524P.TCT

### **Layout Guidelines for Optimum ESD Protection**

Good circuit board layout is critical not only for signal integrity, but also for effective suppression of ESD induced transients. For optimum ESD protection, the following guidelines are recommended:

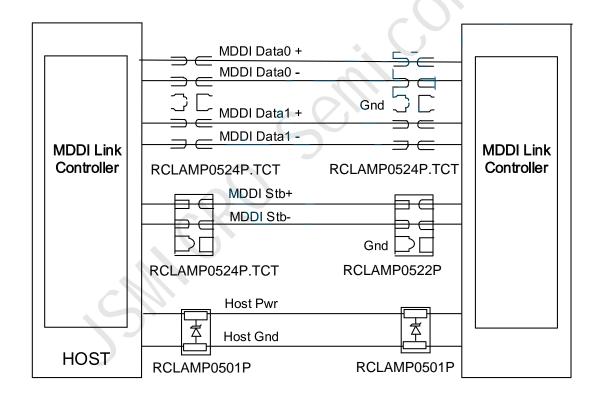
- Place the device as close to the connector as possible. This practice restricts ESD coupling into adjacent traces and reduces parasitic inductance.
- The ESD transient return path to ground should be kept as short as possible. Whenever possible, use multiple micro vias connected directly from the device ground pad to the ground plane.
- Avoid running critical signals near board edges.



## **Application Information (cont)**

#### Protecting MDDI Ports with RCLAMP0524P and RCLAMP0522P

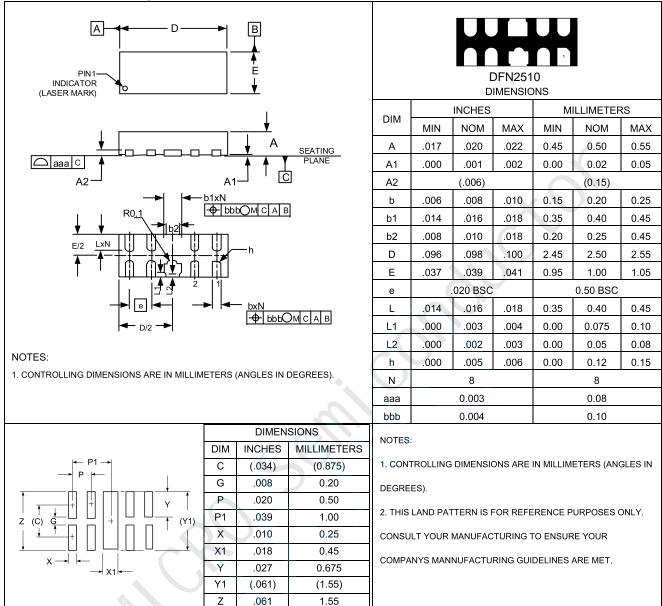
The small package size and low capacitance of the RCLAMP0524P and RCLAMP0522P make them ideal for high-speed lines in portable applications. One such application is the protection of MDDI ports in cellular phones. MDDI is a serial data interface operating at 480Mb/s per line pair. The lines are scalable for increased speed and display resolution. A MDDI port protection example is shown in Figure 5. The RCLAMP0524P is used to protect two differential line pairs while an RCLAMP0522P is used to protect the MDDI strobe lines. Note that devices are used on both the main board and LCD side of the MDDI port. Devices on the main board are needed to protect the MDDI controller in the Base band processor and devices on the LCD board to protect MDDI controller in LCD module. A single line TVS such as the DW05D5-E is used to protect the MDDI power line. The protection devices should be placed close to the connector of each board. Traces are routed directly through each device, minimizing parasitic inductance. Connections to the ground plane should be made with multiple micro vias when possible.



MDDI Port Protection



### **Outline Drawing: DFN2510**



## **Marking Codes**

Part Number	RCLAMP0524P.TCT	Marking Code	5024P

## **Package Information**

Qty: 3000/REEL

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ISMB33CAT3G-XYZ MMAD1108/TR13 5KP100A 5KP15A 5KP18A 5KP48A